

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.75092	100.0	25
			Subtotal	1.75092	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02328	0.04	0.3324
	Copper alloy	Iron (Fe)	7439-89-6	0.0582	0.1	0.831
	Copper alloy	Copper (Cu)	7440-50-8	58.11898	99.86	829.8366
			Subtotal	58.20046	100	831
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.42742	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.3033	16.0	90
	Filler	Silica fused	60676-86-0	29.54672	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11819	0.3	1.6875
			Subtotal	39.39563	100	562.5
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.32217	100.0	4.6
			Subtotal	0.32217	100	4.6
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.30816	100.0	4.4
			Subtotal	0.30816	100	4.4
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00113	5.0	0.01618
	Lead alloy	Silver (Ag)	7440-22-4	0.00057	2.5	0.00809
	Lead alloy	Lead (Pb)	7439-92-1	0.02097	92.5	0.29938
			Subtotal	0.02267	100	0.32365
			Total	100.00001	100	1427.82365

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